

< HIGH VOLTAGE DIODE MODULES >

RM1500HE-66F

HIGH POWER SWITCHING USE
INSULATED TYPE

High Voltage Diode Modules

RM1500HE-66F



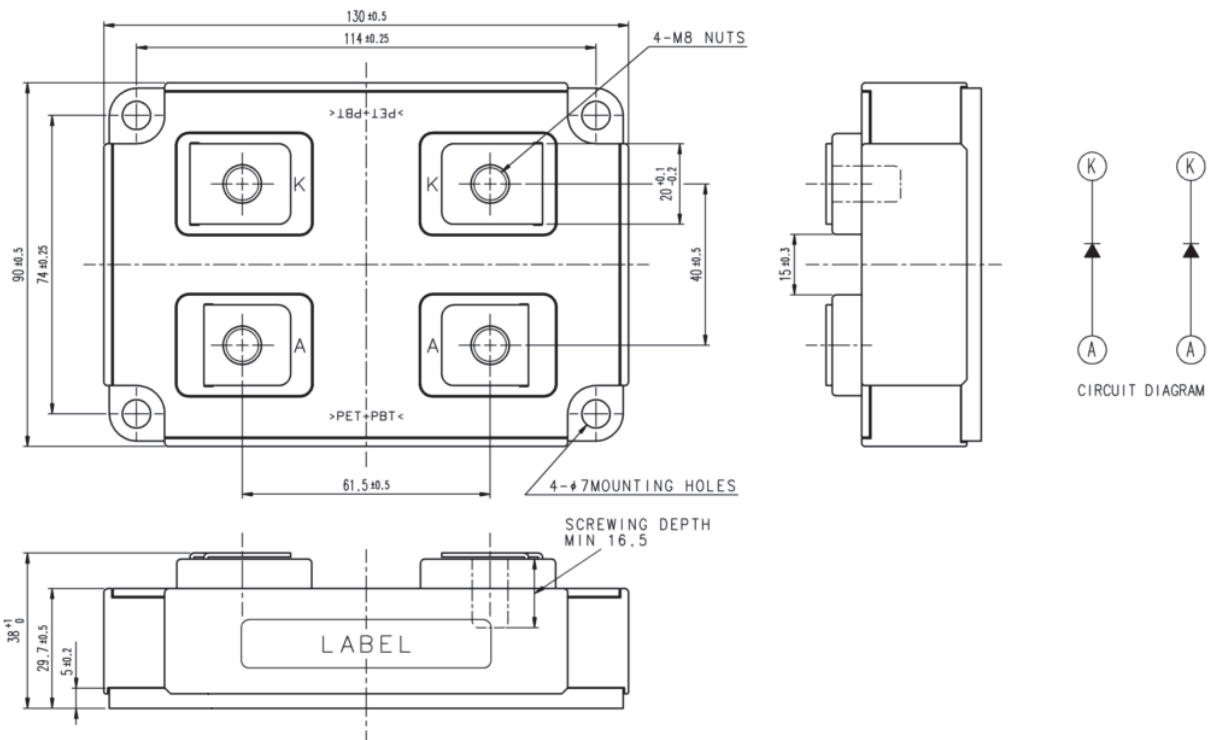
- I_F1500A
- V_{RRM}3300V
- 1-element in a Pack
- Insulated Type
- Soft Recovery Diode
- AISiC Baseplate

APPLICATION

Traction drives, High Reliability Converters / Inverters, DC choppers

OUTLINE DRAWING & CIRCUIT DIAGRAM

Dimensions in mm



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MAXIMUM RATINGS

Symbol	Item	Conditions	Ratings	Unit
V _{RRM}	Repetitive peak reverse voltage	T _J = -40 ... +150°C	3300	V
		T _J = -50°C	3200	
V _{RSM}	Non-repetitive peak reverse voltage	T _J = -40 ... +150°C	3300	V
		T _J = -50°C	3200	
I _F	Forward current	DC, T _C = 75°C	1500	A
I _{FRM}		Pulse (Note 1)	3000	A
I _{FSM}	Surge (non-repetitive) forward current	T _{J,start} = 25°C, t _p = 8.3 ms, Half-sine wave, V _R = 0 V	12000	A
I _t ²	Surge current load integral		598	kA ² s
V _{iso}	Isolation voltage	RMS, sinusoidal, f = 60 Hz, t = 1 min.	6000	V
V _e	Partial discharge extinction voltage	RMS, sinusoidal, f = 60 Hz, Q _{PD} ≤ 10 pC	2400	V
T _J	Junction temperature		-50 ~ +150	°C
T _{opp}	Operating junction temperature		-50 ~ +150	°C
T _{stg}	Storage temperature		-55 ~ +150	°C

ELECTRICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
I _{RRM}	Repetitive reverse current	V _{RM} = V _{RRM}	T _J = 25°C	—	5.0	mA
			T _J = 150°C	—	12.0	
V _{FM}	Forward voltage	I _F = 1500 A (Note 2)	T _J = 25°C	—	3.20	V
			T _J = 150°C	—	2.70	
t _{rr}	Reverse recovery time	V _{CC} = 1500 V I _F = 1500 A L _s = 100 nH	T _J = 25°C	—	—	μs
			T _J = 150°C	—	0.9	
Q _{rr}	Reverse recovery charge	-d _I /d _t = 4400 A/μs @ T _J = 150°C	T _J = 25°C	—	—	μC
			T _J = 150°C	—	1300	
E _{rec}	Reverse recovery energy (Note 3)	Inductive load	T _J = 25°C	—	—	J
			T _J = 150°C	—	1.35	

THERMAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
R _{th(j-c)}	Thermal resistance	Junction to Case	—	—	14.5	K/kW
R _{th(c-s)}	Contact thermal resistance	Case to heat sink, λ _{grease} = 1 W/m ² ·k D _(c-s) = 100 μm	—	15.0	—	K/kW

MECHANICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
M _t	Mounting torque	M8 : Main terminals screw M6 : Mounting screw	6.7	—	10.8	N·m
M _s			2.9	—	3.4	
m	Mass		—	0.66	—	kg
CTI	Comparative tracking index		600	—	—	—
d _a	Clearance		19.5	—	—	mm
d _s	Creepage distance		32.0	—	—	mm
L _{PAK}	Parasitic stray inductance		—	17.0	—	nH
R _{AA'+KK'}	Internal lead resistance	T _C = 25°C	—	0.16	—	mΩ

Note 1. Pulse width and repetition rate should be such that junction temperature (T_J) does not exceed T_{opmax} rating (150°C).

Note 2. Pulse width and repetition rate should be such as to cause negligible temperature rise.

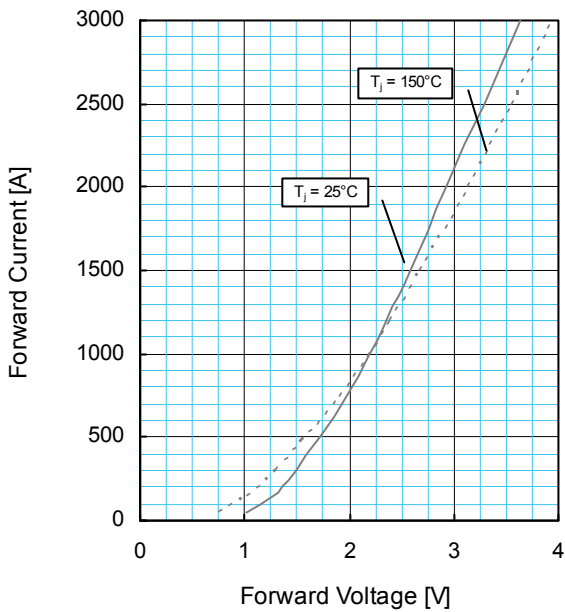
Note 3. E_{rec} is the integral of 0.1V_R × 0.1I_F × dt.

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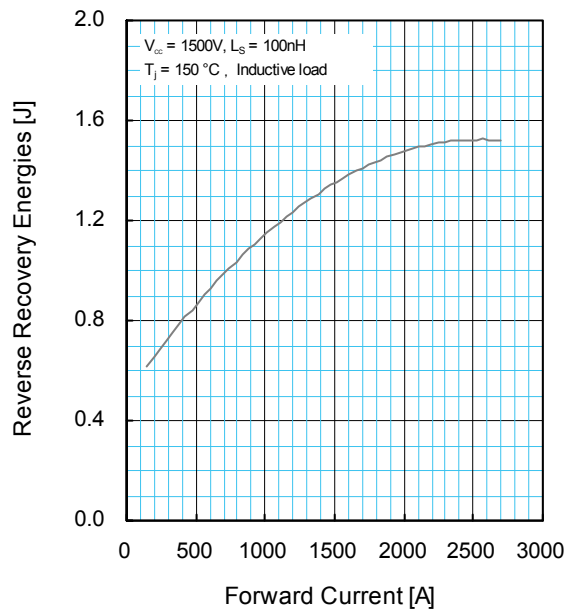
HIGH POWER SWITCHING USE
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PERFORMANCE CURVES

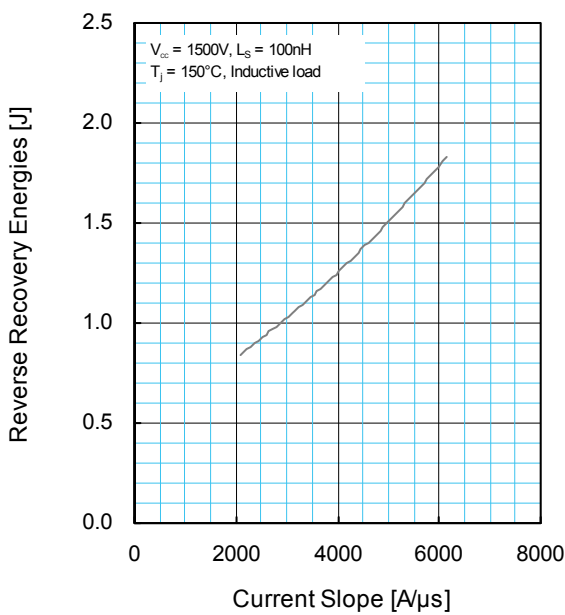
FORWARD CHARACTERISTICS (TYPICAL)



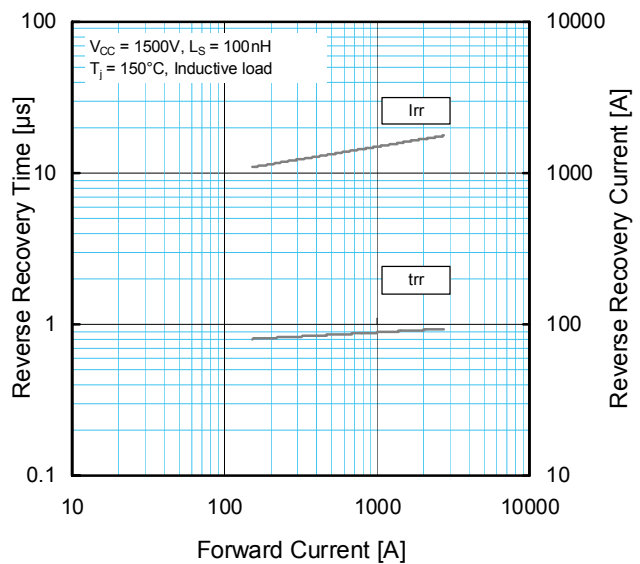
REVERSE RECOVERY ENERGY CHARACTERISTICS (TYPICAL)



REVERSE RECOVERY CHARACTERISTICS (TYPICAL)

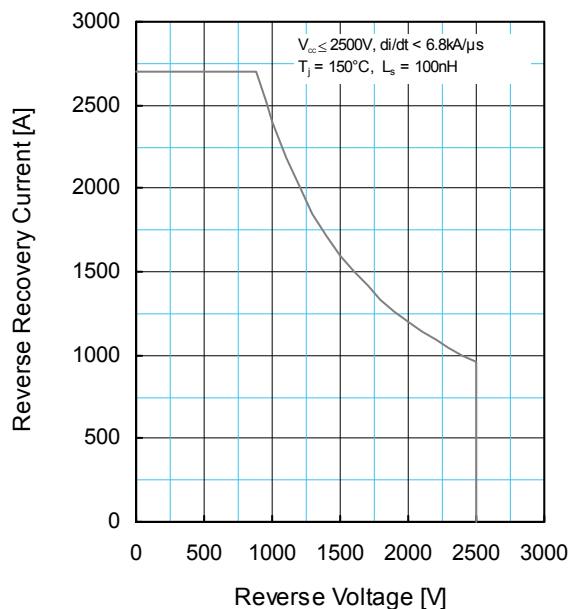


REVERSE RECOVERY CHARACTERISTICS (TYPICAL)

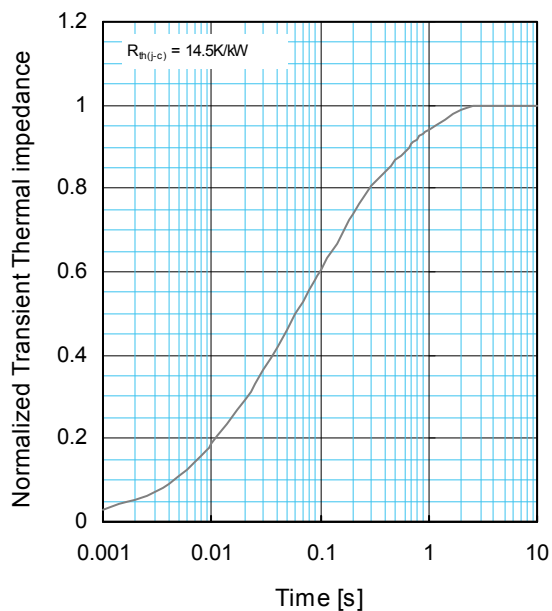


PERFORMANCE CURVES

**REVERSE RECOVERY
SAFE OPERATING AREA (RRSOA)**



**TRANSIENT THERMAL IMPEDANCE
CHARACTERISTICS**



$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i \left\{ 1 - \exp\left(-\frac{t}{\tau_i}\right) \right\}$$

	1	2	3	4
R_i [K/kW]	0.0096	0.1893	0.4044	0.3967
τ_i [sec]	0.0001	0.0058	0.0602	0.3512

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